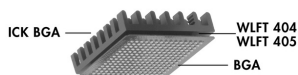


Data sheet Product ICK BGA 25 x 25 x 6



Heatsinks and active heatsinks for processors>Heatsinks for BGAs
 25 x 25 x 6 mm, for IC design BGA and others

Features

way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	25 mm
height:	6 mm
plate thickness:	1.8 mm
length:	25 mm
thermal resistance:	21.25 - 7.75 K/W
dissipation loss:	2.8 W
surface:	black anodised

Technical Drawing

